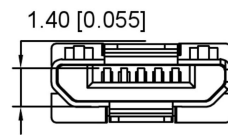
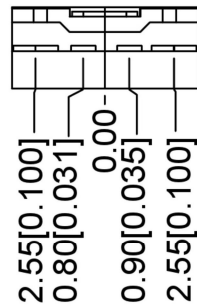
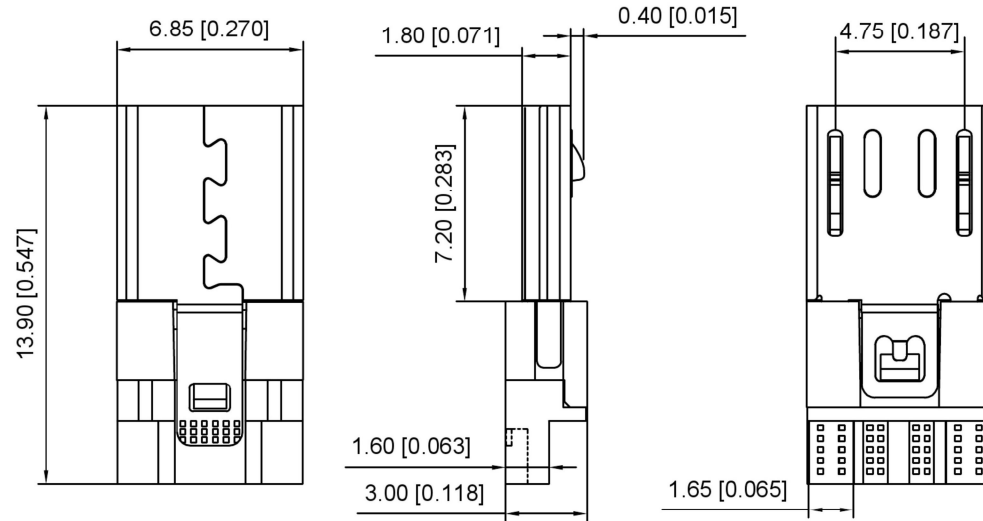


U251-04XN-4BSG86

1:AU 1U"
6:AU 30U"



NOTES:

1.Material:

- 1.1:Housing Material:LCP+30%G.F BLACK UL94-V0
- 1.2:Molding::LCP+30%G.F BLACK UL94-V0
- 1.3:Metallic Shell:SUS304, T=0.20±0.02mm.
- 1.4:SPRING:SUS301, T=0.35±0.05mm.
- 1.5>Contact Terminal:H65,T=0.20±0.02mm

2.Finish:

- 2.1 Contact Terminal:Test point:Ni 50u"/Au 1~3u" MIN
Soldering area:Ni 50u"/Tin(PB Free) 100u" MIN.
The other area:Ni 50u" MIN.
- 2.2 Metallic Shell : Ni 60u" MIN.

3.Specification:

3.1:Rating:

Rated voltage:AC 100V. Rated current:1A.

3.2:Electrical:

- Contact resistance:
50mΩ MAX. at 20mV MAX, 50mA.
- Insulation resistance:
100MΩ MIN. at 500V DC for 1Minute.
- Dielectric withstanding voltang:
No discharge,flashover or breakdown
at 500V/AC 1Minute.

3.3:MECHANICAL:

- INSERTION FORCE : 35N Max.
- EXTRACTION FORCE : 8N Min.
- DURABILITY : 10000 Cycles .

				ANGLAR	±5°	DSND		SCALE: N/A	MODEL TYPE: MICRO USB			
				L ≤ 4	±0.2	DWN		VIEW:	PART NO.:			
				4 < L ≤ 16	±0.3	CHKD		UNIT: mm/in	DWG NO.:			
				16 < L ≤ 63	±0.4	APPD		SIZE: A4				
				L > 63	±0.5				WEIGHT	SHEET	REVISION	
DESCRIPTION				DATE	REVISED	APPROVED	UNSPECIFIED TOLERANCES					
REVISIONS							KE SI DA ELECTRONIC TECHNOLOGY CO., LTD			1/1	A0	
WWW.BODONGKAIGUAN.NET				WWW.CKJACK.COM			WWW.KSDKG.COM					



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